

PCS3P7303A

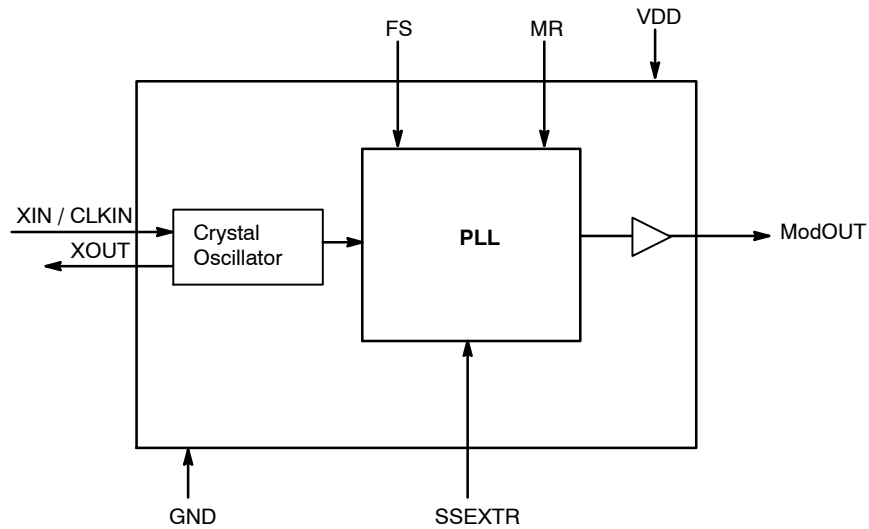


Figure 1. Block Diagram

Table 1. PIN DESCRIPTION

Pin #	Pin Name	Type	Description
1	XIN / CLKIN	Input	Crystal connection or External reference clock input.
2	XOUT	Output	Crystal connection. If using an external reference, this pin should be left open.
3	FS	Input	Frequency Select. Pull LOW to select Low Frequency range. Selects High Frequency range when pulled HIGH. Has an internal pull-up resistor. (See <i>Frequency Selection table</i> for details.)
4	GND	Power	Ground.
5	ModOUT	Output	Buffered Modulated clock output.
6	MR	input	Modulation Rate Select. When LOW selects Low Modulation Rate. Selects High Modulation Rate when pulled HIGH. Has an internal pull-down resistor.
7	SSEXTR	Input	Analog Deviation Selection through external resistor to GND.
8	VDD	Power	2.5 V / 3.3 V supply Voltage.

Table 2. FREQUENCY SELECTION TABLE

VDD (V)	FS	Frequency (MHz)
2.5	0	10 – 35
	1	30 – 70
3.3	0	10 – 40
	1	30 – 80

Table 3. ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Rating	Unit
VDD, V _{IN}	Voltage on any input pin with respect to Ground	–0.5 to +4.6	V
T _{STG}	Storage temperature	–65 to +125	°C
T _s	Max. Soldering Temperature (10 sec)	260	°C
T _J	Junction Temperature	150	°C
T _{DV}	Static Discharge Voltage (As per JEDEC STD22– A114–B)	2	kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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Table 4. OPERATING CONDITIONS

Parameter	Description	Min	Max	Unit
VDD	Supply Voltage	2.3	3.6	V
T _A	Operating Temperature (Ambient Temperature)	-25	+85	°C
C _L	Load Capacitance		10	pF
C _{IN}	Input Capacitance		7	pF

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 5. DC ELECTRICAL CHARACTERISTICS FOR 2.5 V

Parameter	Description	Test Conditions	Min	Typ	Max	Units
VDD	Supply Voltage		2.3	2.5	2.7	V
V _{IL}	Input LOW Voltage				0.7	V
V _{IH}	Input HIGH Voltage		1.7			V
I _{IL}	Input LOW Current	V _{IN} = 0 V			-50	μA
I _{IH}	Input HIGH Current	V _{IN} = V _{DD}			50	μA
V _{OL}	Output LOW Voltage	I _{OL} = 8 mA			0.6	V
V _{OH}	Output HIGH Voltage	I _{OH} = -8 mA	1.8			V
I _{CC}	Static Supply Current	XIN / CLKIN pulled low			500	μA
I _{DD}	Dynamic Supply Current	Unloaded Output	FS = 0; @ 10 MHz		5	mA
			FS = 1; @ 70 MHz		12	
Z _O	Output Impedance			45		Ω

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Table 6. SWITCHING CHARACTERISTICS FOR 2.5 V

Parameter	Test Conditions			Min	Typ	Max	Units
Input Frequency (Note 1) / ModOUT	FS = 0			10		35	MHz
	FS = 1			30		70	
Duty Cycle (Notes 2, 3)	Measured at V _{DD} /2			45	50	55	%
Output Rise Time (Notes 2, 3)	Measured between 20% to 80%				1.75	2.5	nS
Output Fall Time (Notes 2, 3)	Measured between 80% to 20%				1.0	1.6	nS
Cycle-to-Cycle Jitter (Note 3)	Unloaded output	FS = 0	10 MHz		±450	±600	pS
			35 MHz		±125	±250	
		FS = 1	30 MHz		±225	±350	
			70 MHz		±150	±300	
PLL Lock Time (Note 3)	Stable power supply, valid clock presented on XIN / CLKIN					3	mS

1. Functionality with Crystal is guaranteed by design and characterization. Not 100% tested in production.

2. All parameters are specified with 10 pF loaded outputs.

3. Parameter is guaranteed by design and characterization. Not 100% tested in production.

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Table 7. DC ELECTRICAL CHARACTERISTICS FOR 3.3 V

Parameter	Description	Test Conditions		Min	Typ	Max	Units
VDD	Supply Voltage			3.0	3.3	3.6	V
V _{IL}	Input LOW Voltage					0.8	V
V _{IH}	Input HIGH Voltage			2.0			V
I _{IL}	Input LOW Current	V _{IN} = 0 V				-50	μA
I _{IH}	Input HIGH Current	V _{IN} = V _{DD}				50	μA
V _{OL}	Output LOW Voltage	I _{OL} = 8 mA				0.4	V
V _{OH}	Output HIGH Voltage	I _{OH} = -8 mA		2.4			V
I _{CC}	Static Supply Current	XIN / CLKIN pulled low				700	μA
I _{DD}	Dynamic Supply Current	Unloaded Output	FS = 0; @ 10 MHz			7	mA
			FS = 1; @ 80 MHz			20	
Z _O	Output Impedance				35		Ω

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Table 8. SWITCHING CHARACTERISTICS FOR 3.3 V

Parameter	Test Conditions			Min	Typ	Max	Units
Input Frequency (Note 1) / ModOUT	FS = 0			10		40	MHz
	FS = 1			30		80	
Duty Cycle (Notes 2, 3)	Measured at V _{DD} /2			45	50	55	%
Output Rise Time (Notes 2, 3)	Measured between 20% to 80%				1.3	2	nS
Output Fall Time (Notes 2, 3)	Measured between 80% to 20%				0.9	1.3	nS
Cycle-to-Cycle Jitter (Note 3)	Unloaded output	FS = 0	10 MHz		±450	±600	pS
			40 MHz		±125	±250	
		FS = 1	30 MHz		±225	±350	
			80 MHz		±125	±250	
PLL Lock Time (Note 3)	Stable power supply, valid clock presented on XIN / CLKIN					3	mS

4. Functionality with Crystal is guaranteed by design and characterization. Not 100% tested in production.

5. All parameters are specified with 10 pF loaded outputs.

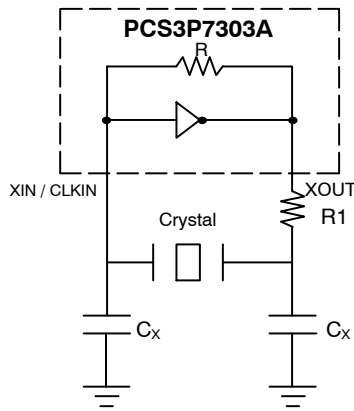
6. Parameter is guaranteed by design and characterization. Not 100% tested in production.

Table 9. TYPICAL CRYSTAL SPECIFICATIONS

Fundamental AT Cut Parallel Resonant Crystal	
Nominal frequency	25 MHz
Frequency tolerance	±50 ppm or better at 25°C
Operating temperature range	-25°C to +85°C
Storage temperature	-40°C to +85°C
Load capacitance (C _P)	18 pF
Shunt capacitance	7 pF maximum
ESR	25 Ω

NOTE: C_L is the Load Capacitance and R1 is used to prevent oscillations at overtone frequency of the Fundamental frequency.

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$C_X = 2 * (C_P - C_S)$,
Where C_P = Load capacitance of crystal from crystal vendor datasheet.
 C_S = Stray capacitance due to C_{IN} , PCB, Trace, etc.

Figure 2. Typical Crystal Interface Circuit

Switching Waveforms

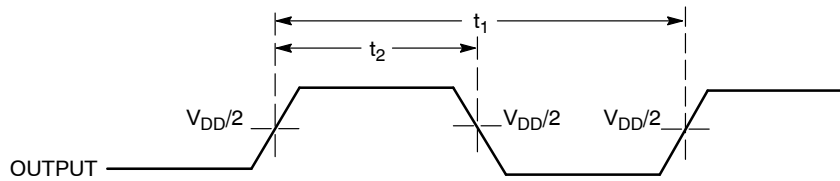


Figure 3. Duty Cycle Timing

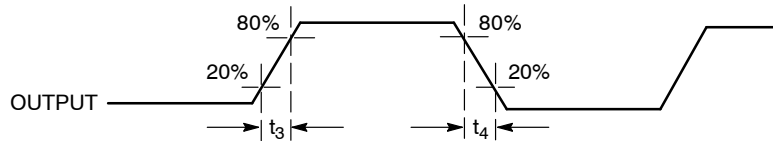
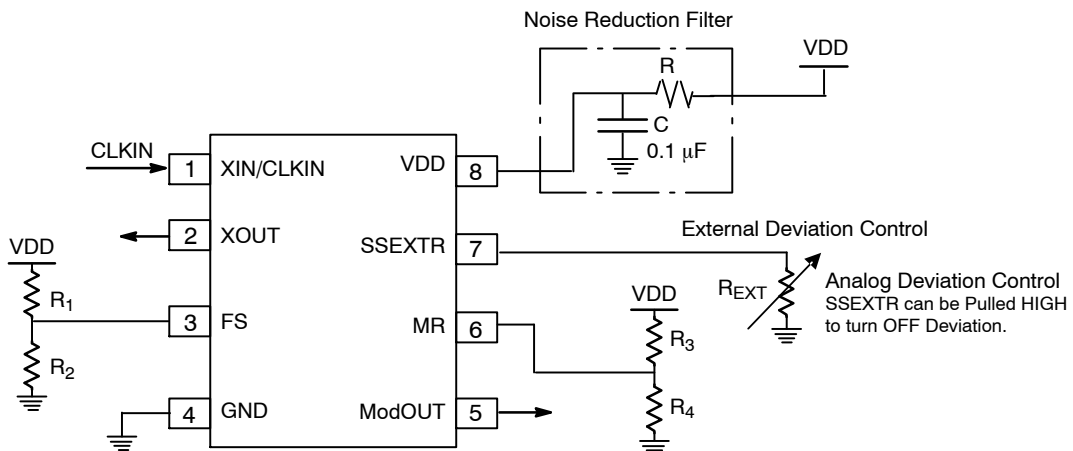


Figure 4. Output Rise/Fall Time

Application Schematic



Note: FS (Pin#3) MR (Pin#6): Connect to VDD or GND

Refer to Pin Description table for Functionality details.

Use 0 Ω resistor at either R_1 or R_2 to configure FS.

Use 0 Ω resistor at either R_3 or R_4 to configure MR.

Figure 5. Application Schematic

Charts

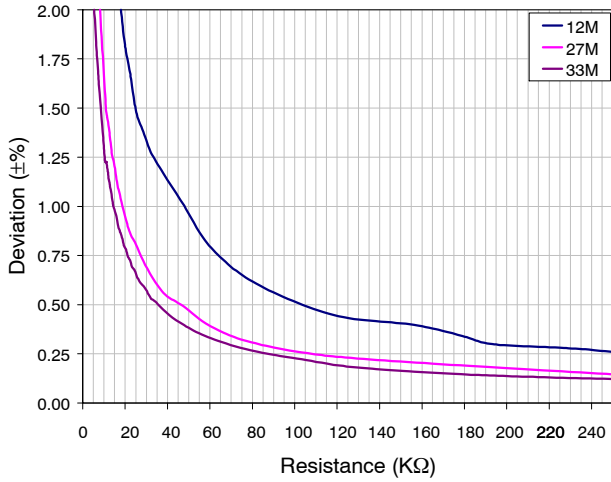


Figure 6. Deviation vs. Resistance (FS = 0, MR = 0)

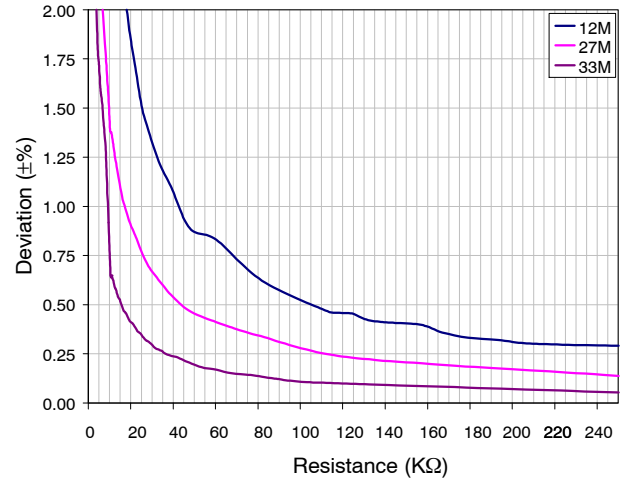


Figure 7. Deviation vs. Resistance (FS = 0, MR = 1)

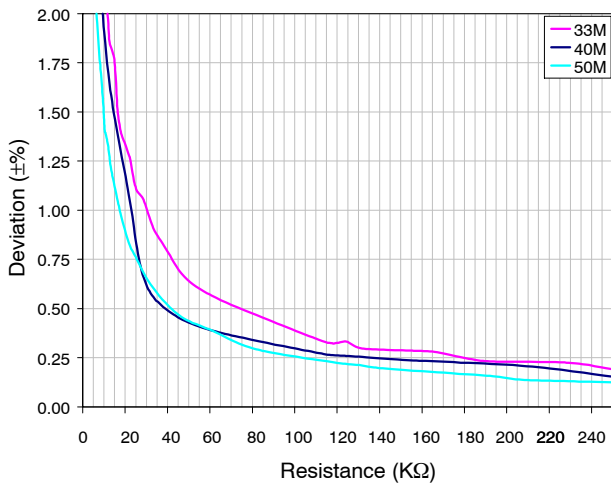


Figure 8. Deviation vs. Resistance (FS = 1, MR = 0)

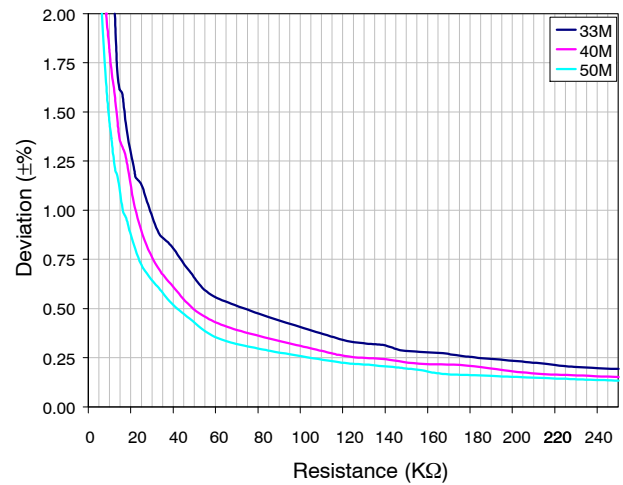


Figure 9. Deviation vs. Resistance (FS = 1, MR = 1)

NOTE: Device to Device variation of Deviation is $\pm 10\%$ (0°C to 70°C) and $\pm 25\%$ (-25°C to $+85^{\circ}\text{C}$)

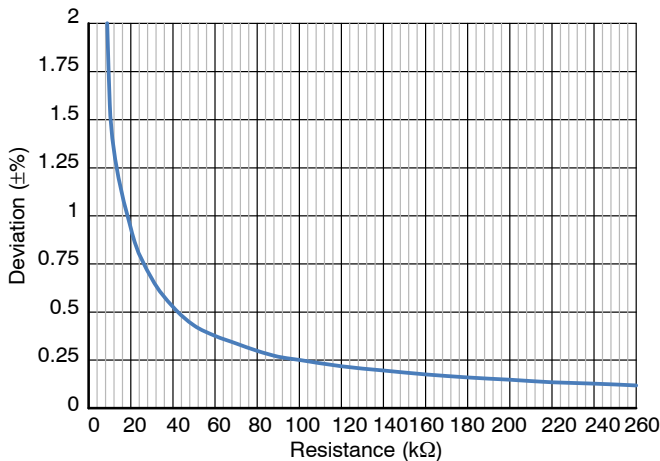


Figure 10. Deviation vs. Resistance (FS = 1, MR = 0) $V_{DD} = 3.3\text{ V}$

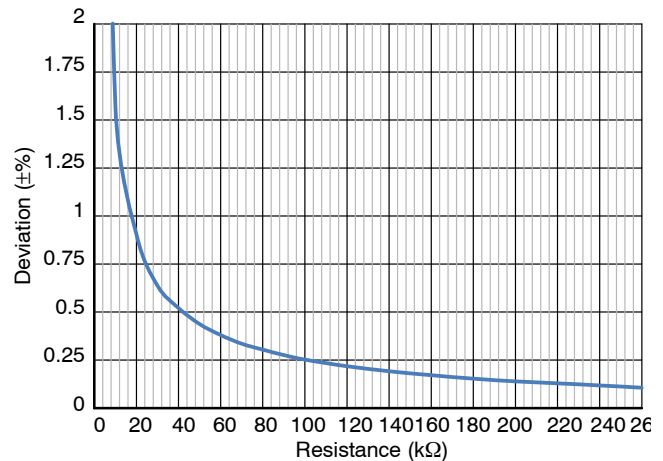


Figure 11. Deviation vs. Resistance (FS = 1, MR = 1) $V_{DD} = 3.3\text{ V}$

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Table 10. ORDERING INFORMATION

Part Number	Marking	Temperature	Package	Shipping†
PCS3P7303AG-08TR	BKL	-25°C to +85°C	8-pin TSSOP (Pb-Free)	Tape & Reel
PCS3P7303AG-08TT	BKL	-25°C to +85°C	8-pin TSSOP (Pb-Free)	Tube
PCS3P7303AG-08CR	BK	-25°C to +85°C	8L WDFN (2 mm x 2 mm) (Pb-Free)	Tape & Reel

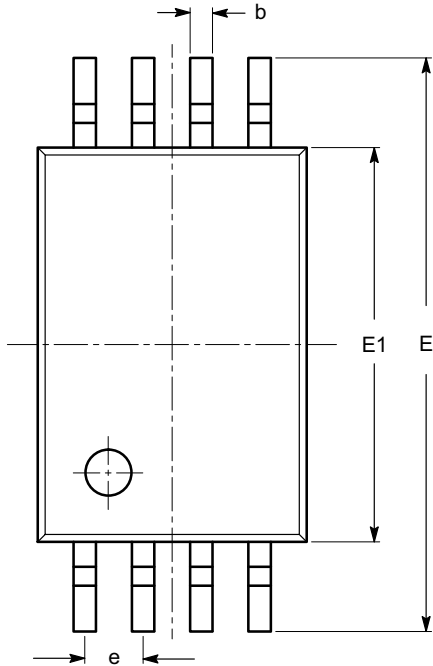
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NOTE: A “microdot” placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-Free.

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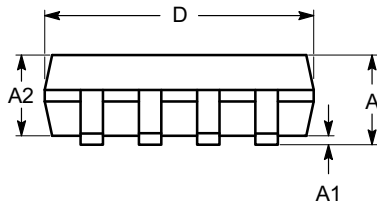
PACKAGE DIMENSIONS

TSSOP8, 4.4x3
CASE 948AL
ISSUE O

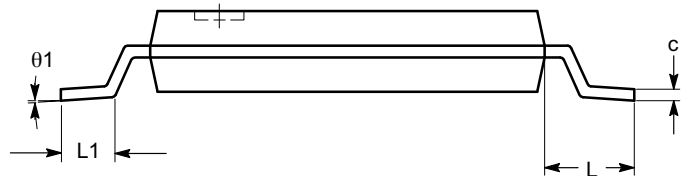


SYMBOL	MIN	NOM	MAX
A			1.20
A1	0.05		0.15
A2	0.80	0.90	1.05
b	0.19		0.30
c	0.09		0.20
D	2.90	3.00	3.10
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
e	0.65 BSC		
L	1.00 REF		
L1	0.50	0.60	0.75
θ	0°		8°

TOP VIEW



SIDE VIEW



END VIEW

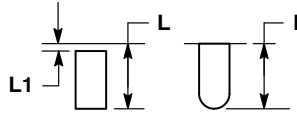
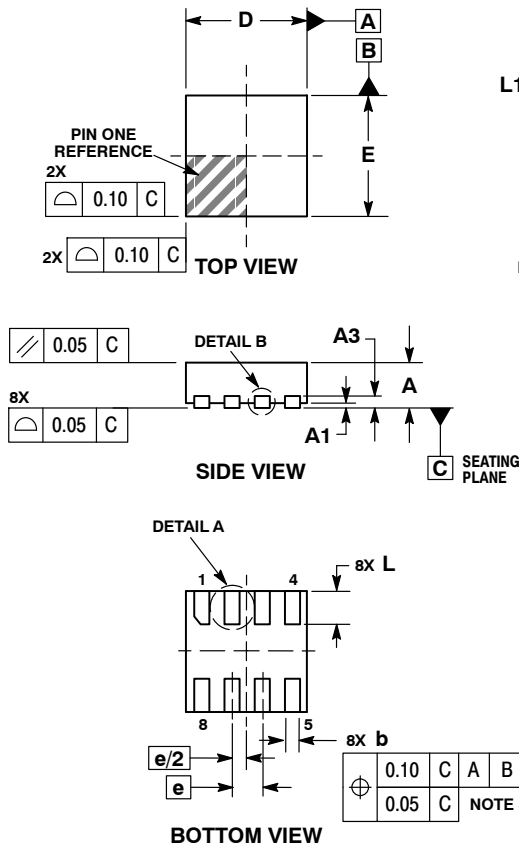
Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153.

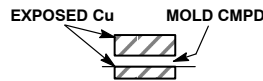
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PACKAGE DIMENSIONS

WDFN8 2x2, 0.5P CASE 511AQ ISSUE A



DETAIL A
OPTIONAL
CONSTRUCTIONS

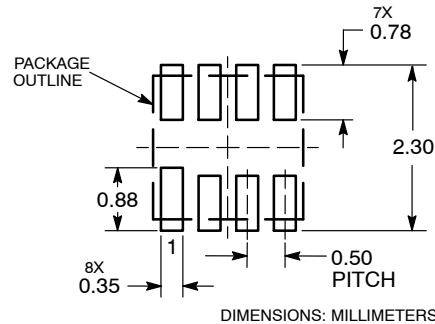


DETAIL B
OPTIONAL
CONSTRUCTION

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	2.00	BSC
E	2.00	BSC
e	0.50	BSC
L	0.50	0.60
L1	---	0.15

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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